



Final Product Change Notification

202403007F01 : Technology Transfer from NXP Oak Hill Fab to the NXP ICN8 Fab in Nijmegen

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 24, 2024 **Effective Date:** Jun 22, 2024

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Management summary

LDMOS technology transfer from NXP Oak Hill fab to the NXP ICN8 fab in Nijmegen

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

Notification Overview

Description

NXP Semiconductors would like to announce the completion of the technology transfer from the legacy NXP Oak Hill fab to the NXP ICN8 fab in Nijmegen, Netherlands, as announced in General Notification 202009009G and CIN 202305017I.

With the qualification of the technology transfer complete, we are now able to provide more precise dates for the availability of customer samples and the expected date at which support of production devices from the ICN8 fab can begin.

The enclosed file includes those devices containing both LDMOS die and/or Integrated Passive Devices (IPD). Samples will be available per the timeframe indicated in the attached spreadsheet. Production of those finished goods using die from the ICN8 fab will be transferred dependent on the consumption rate of existing die inventories.

Customer acceptance is requested within 90 days of the "Release to Production" date listed to enable the execution to supply devices from production as indicated.

Reason

Announce the completion the internal LDMOS technology transfer and the sample availability schedule

Identification of Affected Products

Product identification does not change

Date Code will be used to determine manufacturing locations

Product Availability

Sample Information

Samples availability differs by product-see attached sample plan

Production

Shipment dates are product specific, see attached plan

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Apr 23, 2024.

In accordance with JEDEC J-STD-048, Potential Last Time Buy orders shall be placed before .

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
935450722528	A5G18H605W19NR3	A5G18H605W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935426992128	A3G23H500W17SR3	A3G23H500W17SR3	2.3GHz GaN NI7805-4S2S	HCFM6CV	SOT1799-6	DOD	No	BLRF
935417302128	A3G26H502W17SR3	A3G26H502W17SR3	2.6GHz GaN NI7805-4S2S	HCFM6CV	SOT1799-6	DOD	No	BLRF
935457124528	A5G18H610W19NR3	A5G18H610W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935462141528	A5G19H605W19NR3	A5G19H605W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935417778128	A3G26H350W17SR3	A3G26H350W17SR3	2.6GHz GaN NI7805-4S2S	HCFM6CV	SOT1799-6	DOD	No	BLRF
935461133528	A5G26H605W19NR3	A5G26H605W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935451705528	A5G21H605W19NR3	A5G21H605W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935450755528	A5G08H800W19NR3	A5G08H800W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935449319528	A5G07H800W19NR3	A5G07H800W19NR3	GaN OM780-4S4S	HPFM8	SOT2082-1	RFS	No	BLRF
935432729518	A5G35H120NT2	A5G35H120NT2	GaN DFN7X10 10Lead	H(L)PwrSON10	SOT2053-1	RFS	No	BLRF
935427147528	A5G35S008NT6	A5G35S008NT6	GaN DFN4.5X4.0 6L	H(L)SON6	SOT2040-1	RFS	No	BLRF
935421037528	A5G38H045NT4	A5G38H045NT4	DMS GaN DFN7X6.5 6L	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935448933528	A5G38H055NT4	A5G38H055NT4	GaN DFN7X6.5 6L	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935424245528	A5G35H110NT4	A5G35H110NT4	GaN DFN7X10 10Lead	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935432674528	A5G37H110NT4	A5G37H110NT4	DMS 3.0 32T DFN7X6.5	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935433224528	A5G26H110NT4	A5G26H110NT4	DMS GaN DFN7X6.5 6L	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935432677528	A5G26S008NT6	A5G26S008NT6	GaN DFN4.5X4.0 6L	H(L)SON6	SOT2040-1	RFS	No	BLRF
935433396528	A5G23H065NT4	A5G23H065NT4	GaN DFN7X6.5 6L	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935418045528	A5G26S004NT6	A5G26S004NT6	GaN Driver DFN4.5X4.0 6L	H(L)SON6	SOT2040-1	RFS	No	BLRF
935442486528	A5G23H110NT4	A5G23H110NT4	DMS GaN DFN7X6.5 6L	H(L)PwrSON6	SOT2030-1	RFS	No	BLRF
935443507528	AFSC5G23E39T2	AFSC5G23E39T2	10x6 SiP Module	H(L)LGA27SIP	SOT1831-2	RFS	No	BLRF
935457871528	A5M20TG042T1	A5M20TG042T1	20x16 GaN MPM	HLGA25SIP	SOT2171-1	CQS	No	BLRF
935369413528	AFSC5G35D37T2	AFSC5G35D37T2	10x6 SiP Module	H(L)LGA27SIP	SOT1831-1	RFS	No	BLRF
93537767528	AFSC5G37D37T2	AFSC5G37D37T2	10x6 SiP Module	H(L)LGA27SIP	SOT1831-1	RFS	No	BLRF
935415964528	AFSC5G37E38T2	AFSC5G37E38T2	10x6 Module	H(L)LGA27SIP	SOT1831-2	RFS	No	BLRF
935408976528	AFSC5G35E38T2	AFSC5G35E38T2	10X6 MOLDULE	H(L)LGA27SIP	SOT1831-2	RFS	No	BLRF